

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Ball et al.

Serial No.: 09/736,795

Filed: December 14, 2000

For: METHOD OF DISPOSING CONDUCTIVE BUMPS ONTO A SEMICONDUCTOR DEVICE

Confirmation No.: 6757

Examiner: E. Pert

Group Art Unit: 2829

Attorney Docket No.: 2269-3817.1US

(97-1350.01/US)

Notice of Allowance Mailed:

April 2, 2004

Express Mail Mailing Label No.:

EL 994842599US

Date of Deposit with USPS:

July 1, 2004

Person making Deposit:

Christopher Haughton

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Abstract appear on page 7 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 8 of this paper.

Remarks begin on page 14 of this paper.